

line and the area array electrodes. It also allows suppressing problems such as signal delay, line interference, and increased noise.

Amend the paragraph beginning at page 11, line <sup>16</sup>~~12~~ and ending at page 12, line 1 as follows:

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As shown in Fig. 1, on the periphery of the semiconductor chip 10 are formed a plurality of peripheral electrode pads ± 1a and 1b that are peripheral electrodes. The peripheral electrode pads ± 1a and 1b are connected to various internal circuits (not shown) formed in the semiconductor chip 10 by internal lines (not shown). When inspecting the internal circuits of the semiconductor chip 10, the peripheral electrode pads 1a and 1b ± are used also as input/output terminals for inputting and outputting inspection signals where probe terminals of an inspection device are brought into contact.

Amend the paragraph at page 12, lines 2-19 as follows:

On the inner side of the semiconductor chip 10 surrounded by the peripheral electrode pads 1a and 1b ± are formed internal electrode pads 5. The internal electrode pads 5 are connected to the internal circuits and the peripheral electrode pads 1b ± via